



## Material Content Data Sheet



Halogen-Free

<b>Sales Product Name</b>	BTS3028SDL	<b>Issued</b>	13. May 2021
<b>MA#</b>	MA002245726		
<b>Package</b>	PG-TO252-3-11	<b>Weight*</b>	372.85 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	5.197	1.39	1.39	13937	13937
leadframe	inorganic material	phosphorus	7723-14-0	0.065	0.02		173	
	non noble metal	iron	7439-89-6	0.215	0.06		577	
	non noble metal	copper	7440-50-8	215.017	57.68	57.76	576686	577436
wire	non noble metal	aluminium	7429-90-5	1.865	0.50	0.50	5001	5001
encapsulation	inorganic material	zinc oxide	1314-13-2	1.233	0.33		3308	
	miscellaneous	miscellaneous	-	6.166	1.65		16539	
	plastics	epoxy resin	-	18.499	4.96		49616	
	inorganic material	silicon dioxide	60676-86-0	97.430	26.13	33.07	261312	330775
lead finish	non noble metal	tin	7440-31-5	3.740	1.00	1.00	10031	10031
plating	inorganic material	phosphorus	7723-14-0	0.000			1	
	non noble metal	nickel	7440-02-0	0.091	0.02	0.02	243	244
solder	non noble metal	tin	7440-31-5	0.083	0.02		221	
	noble metal	silver	7440-22-4	0.103	0.03		277	
	non noble metal	lead	7439-92-1	3.943	1.06	1.11	10576	11074
heatspreader	inorganic material	phosphorus	7723-14-0	0.006			15	
	non noble metal	iron	7439-89-6	0.019	0.01		52	
	non noble metal	copper	7440-50-8	19.177	5.14	5.15	51435	51502
*deviation	< 10%	Sum in total:				100.00		1000000

### Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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